

Title (en)

Method of soldering lead wires to ceramic components

Title (de)

Verfahren zum Anlöten von Anschlussdrähten an keramische Bauelemente

Title (fr)

Procédé pour souder des fils de connexion à des composants céramiques

Publication

**EP 0828262 A1 19980311 (DE)**

Application

**EP 97114226 A 19970818**

Priority

DE 19636577 A 19960909

Abstract (en)

The method involves soldering connector wires to ceramic components. Before soldering, a solder tape (3) provided with a flux agent, is applied to the wire (1) to be soldered. The solder band (3) is preferably attached to the wire (1) using a device (2,4) by means of a mechanical bending process. The solder tape (3) is preferably mechanically fastened to the connection wire (1) using a movable device (2) in which the tape (3) and then the wire (1) are laid, and a counter component (4) which moves relative to the device (2) to bend the tape (3).

Abstract (de)

Bei einem Verfahren zum Anlöten von Anschlußdrähten (1) an keramische Bauelemente wird vor dem Anlöten ein mit einem Flußmittel versehenes Lotband (3) auf den zu verlötenden Anschlußdraht (1) aufgebracht. <IMAGE>

IPC 1-7

**H01C 17/28**; **H01C 1/144**; **H01C 1/14**

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CPC (source: EP)

**H01C 1/1406** (2013.01); **H01C 1/144** (2013.01); **H01C 17/28** (2013.01)

Citation (search report)

- [X] US 4915286 A 19900410 - MENTZER REGIS [FR], et al
- [A] PATENT ABSTRACTS OF JAPAN vol. 011, no. 314 (E - 549) 13 October 1987 (1987-10-13)
- [A] PATENT ABSTRACTS OF JAPAN vol. 010, no. 313 (E - 448) 24 October 1986 (1986-10-24)

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